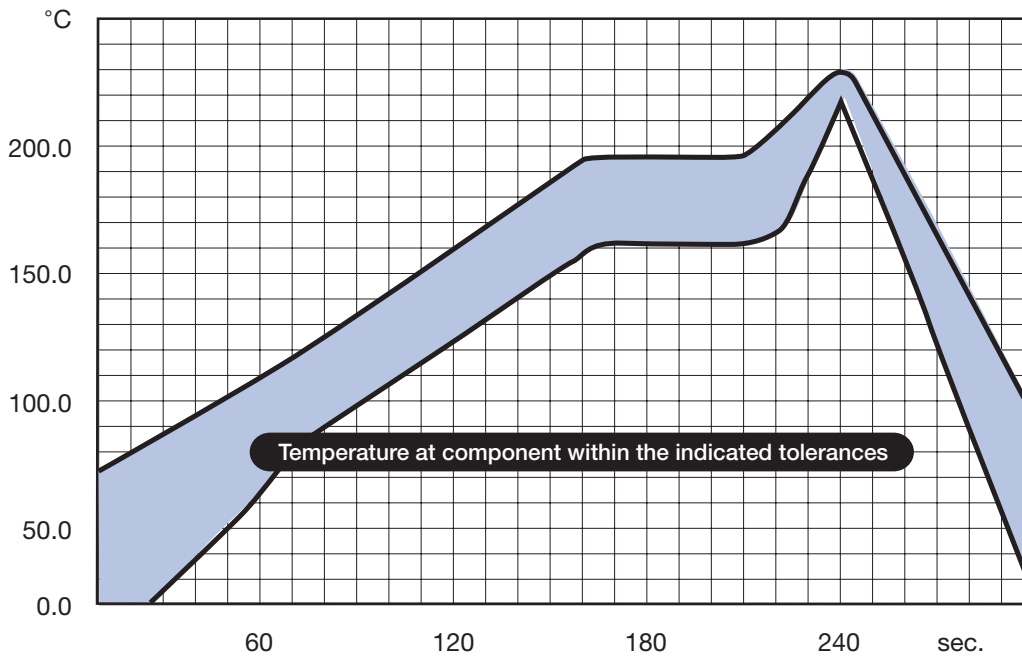


Recommended Temperature Profile at Reflow Soldering



Recommendation for Processing:

- for reflow-soldering the max. temperature is 230°C
- during processing component shall be shielded without direct pressure being applied on the component
 - depending on the size of the component, the cooling period after reaching peak temperature may be extended up to 20 minutes to reach room temperature
 (For conductive glueing please note maximum storage-time periods of components)

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